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Click here for the 3D model.

| Dimensions | |
|------------|------------------|
| Case Code | 4B |
| L | 4.1mm +/-0.38mm |
| W | 6.1mm +/-0.2mm |
| Н | 4.3mm +/-0.38mm |
| S | 0.76mm +/-0.38mm |
| F | 5.3mm +/-0.2mm |
| К | 3.1mm +/-0.38mm |

| Packaging Specifications | |
|--------------------------|------|
| Packaging | Tray |
| Packaging Quantity | 50 |

| General Information | ı |
|------------------------|---|
| Series | TSP |
| Dielectric | Polymer Tantalum |
| Style | Stacked Chip |
| Description | SMD, Polymer, KO, Stacks, High Reliability |
| Features | High Reliability |
| RoHS | No |
| Prop 65 | WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov. |
| SCIP Number | 30e82d35-b509-48ec-8c77-2d5ec01b3abc |
| Termination | Solder Coated |
| Termination (Stack) | Solder Coated |
| AEC-Q200 | No |
| MSL | 3 |

| Specifications | |
|--------------------------|--|
| Capacitance | 400 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 4 VDC (105C), 2.68 VDC (125C) |
| Temperature Range | -55/+125°C |
| Rated Temperature | 105°C |
| Dissipation Factor | 8% 120Hz 25C |
| Failure Rate | N/A |
| Resistance | 20 mOhms (100kHz 25C) |
| Leakage Current | 160 uA (5min 25°C) |
| Testing and Reliability | 4 Cycles At +25C +/-5C Before Voltage Aging |
| | |

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